Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	7084	(wafer or semiconductor or substrate) same (shield or cup or housing or container) near6 (plurality or multiple or several)	US-PGPUB; USPAT	OR	ON	2006/05/18 09:59
L2	5131	(wafer or semiconductor or substrate) same (shield or cup or housing) near6 (plurality or multiple or several)	US-PGPUB; USPAT	OR	ON	2006/05/18 09:59
L3	3191	(wafer or semiconductor or substrate) near10 (shield or cup or housing) near6 (plurality or multiple or several)	US-PGPUB; USPAT	OR	ON	2006/05/18 10:00
L4	94	"134"/\$.ccls. and (wafer or semiconductor or substrate) near10 (shield or cup or housing) near6 (plurality or multiple or several)	US-PGPUB; USPAT	OR	ON	2006/05/18 10:08
L5	123	"134"/\$.ccls. and (wafer or semiconductor or substrate) same (shield or cup or housing) near6 (plurality or multiple or several)	US-PGPUB; USPAT	OR	ON	2006/05/18 10:12
L6	40	"134"/\$.ccls. and (wafer or semiconductor or substrate) same (shield or cup) near6 (plurality or multiple or several)	US-PGPUB; USPAT	OR	ON	2006/05/18 10:26
L7	2341	(wafer or semiconductor or substrate) same (shield\$3) near6 (plurality or multiple or several)	US-PGPUB; USPAT	OR	ON	2006/05/18 10:27
L8	356	(wafer) same (shield\$3) near6 (plurality or multiple or several)	US-PGPUB; USPAT	OR	ON	2006/05/18 10:27
L15	76	(wafer or semiconductor or substrate or workpiece) same (shield\$3 or cup or scatter or hous\$3) near10 (particle or sand or grit) near10 (blast\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/18 10:35
L17	2	"200146998"	EPO; DERWENT	OR	ON	2006/05/18 10:35
L18	2	"2001046998"	EPO; DERWENT	OR	ON	2006/05/18 10:42
L19	3	"2001007068"	EPO; DERWENT	OR	ON	2006/05/18 10:42
L20	4	"2001007068"	EPO; JPO; DERWENT	OR	ON	2006/05/18 12:55

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L21	15	(wafer or semiconductor or substrate or workpiece) same shield\$3 near10 blast\$3	EPO; JPO; DERWENT	OR	ON	2006/05/18 12:55
L22	97	(wafer or semiconductor or substrate or workpiece) same shield\$3 near10 blast\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/18 13:25
L23	74	"6258220"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/18 13:28
L24	6	"5974680"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/18 13:34
L25	0	(wafer or semiconductor or substrate or workpiece) same (blast\$3) near10 (polycarbonate) same shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/18 13:35
L26	1	(wafer or semiconductor or substrate or workpiece) same (blast\$3) same (polycarbonate) same shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/18 13:49
L27	2	(wafer or semiconductor or substrate or workpiece) and (blast\$3) same (polycarbonate) same shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/18 13:36
L28	16	(wafer or semiconductor or substrate or workpiece) and (blast\$3 or textur\$4) same (polycarbonate) same shield	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/18 13:39
L29	32	(wafer or semiconductor or substrate or workpiece) and (blast\$3 or textur\$4) same (polycarbonate) same (shield\$3 or cup or hous\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/18 13:40
L30	16	29 not 28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/18 13:49

						2006/05/15 15 55
L31	2714	(wafer or semiconductor or substrate or workpiece) same (shield\$3 or cup) near10 (groov\$3 or channel\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/18 13:50
L32	27	"134"/\$.ccls. and (wafer or semiconductor or substrate or workpiece) same (shield\$3 or cup) near10 (groov\$3 or channel\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/18 13:59
S1	11	US-4674521-\$.DID. OR US-5727332-\$.DID. OR US-5745946-\$.DID. OR US-5778911-\$.DID. OR US-5846327-\$.DID. OR US-5927305-\$.DID. OR US-5974680-\$.DID. OR US-6114254-\$.DID. OR US-3865298-\$.DID. OR US-3970471-\$.DID. OR US-4694527-\$.DID.	US-PGPUB; USPAT	OR	ON	2006/05/17 12:54
S2	0	S1 and shield and (particle near5 blast\$3)	US-PGPUB; USPAT	OR	ON	2006/05/17 12:54
S3	6	S1 and (shield or cup)	US-PGPUB; USPAT	OR	ON	2006/05/17 12:58
S4	6	S1 and (shield\$3 or cup)	US-PGPUB; USPAT	OR	ON	2006/05/17 13:14
S5	7	S1 and (shield\$3 or cup or particle)	US-PGPUB; USPAT	OR	ON	2006/05/17 13:15
S6	6	S1 and (particle)	US-PGPUB; USPAT	OR	ON	2006/05/17 13:18
S7	190	(wafer or semiconductor or substrate or workpiece) and (shield or cup or scatter) same (particle or sand or grit) near10 (blast\$3)	US-PGPUB; USPAT	OR	ON	2006/05/17 15:28
S8	4	US-5317778-\$.DID. OR US-5810028-\$.DID. OR US-5860178-\$.DID. OR US-6516816-\$.DID.	US-PGPUB; USPAT	OR	ON	2006/05/17 13:20
S9	62	(wafer or semiconductor or substrate or workpiece) same (shield or cup or scatter) same (particle or sand or grit) near10 (blast\$3)	US-PGPUB; USPAT	OR	ON	2006/05/17 14:16

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S10	1	(wafer or semiconductor or substrate or workpiece) same (shield or cup) same (particle or sand or grit) near10 (blast\$3) same hydrophilic	US-PGPUB; USPAT	OR	ON	2006/05/17 13:43
S11	1	(wafer or semiconductor or substrate or workpiece) and (shield or cup) same (particle or sand or grit) near10 (blast\$3) same hydrophilic	US-PGPUB; USPAT	OR	ON	2006/05/17 13:43
S12	190	(wafer or semiconductor or substrate or workpiece) and (shield or cup or scatter) same (particle or sand or grit) near10 (blast\$3)	US-PGPUB; USPAT	OR	ON	2006/05/17 13:44
S13	50	(wafer or semiconductor or substrate or workpiece) same (shield\$3 or cup or scatter or hous\$3) near10 (particle or sand or grit) near10 (blast\$3)	US-PGPUB; USPAT	OR	ON	2006/05/17 14:42
S14	22	S13 not S9	US-PGPUB; USPAT	OR	ON	2006/05/17 14:42
S15	76	(wafer or semiconductor or substrate or workpiece) same (shield\$3 or cup or scatter or hous\$3) near10 (particle or sand or grit) near10 (blast\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 14:48
S16	48	S15 not S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 15:28
S17	36	(wafer or semiconductor or substrate or workpiece) same (shield or cup or scatter) near10 polycarbonate	US-PGPUB; USPAT	OR	ON	2006/05/17 15:43
S18	48	(wafer or semiconductor or substrate or workpiece) same (shield or cup or scatter) near10 polycarbonate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 15:41
S19	12	S18 not S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/05/17 15:41

S20	46	(wafer or semiconductor or substrate or workpiece) same (shield or cup or scatter) near15 polycarbonate	US-PGPUB; USPAT	OR	ON	2006/05/17 15:43
S21	10	S20 not S17	US-PGPUB; USPAT	OR	ON	2006/05/17 15:44
S22	78	134/902,182.ccls. and (wafer or semiconductor or substrate) same shield	US-PGPUB; USPAT	OR	ON	2006/05/17 15:45
S23	748	134/902,182.ccls. and (wafer or semiconductor or substrate) same (shield or cup or housing or container)	US-PGPUB; USPAT	OR	ON	2006/05/17 15:45
S24	10	134/902,182.ccls. and (wafer or semiconductor or substrate) same (shield or cup or housing or container) same (blast\$3 or polycarbonate)	US-PGPUB; USPAT	OR	ON	2006/05/18 09:58